12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20130628003
Assembly/Test Offload for the LM3401MM* Product Family at AP1 and ASESH
Change Notification / Sample Request

Date: 7/2/2013
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

20130628003
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
LM3401MM/NOPB	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20130628003	**PCN Date:**	07/02/2013
Title:	Assembly/Test Offload for the LM3401MM* Product Family at AP1 and ASESH		
Customer Contact:	PCN Manager	**Phone:** +1(214)480-6037	**Dept:** Quality Services
Proposed 1st Ship Date:	10/02/2013	**Estimated Sample Availability:**	07/03/2013

Change Type:

☒	Assembly Site	☐	Assembly Process	☒	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☒	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process

PCN Details

Description of Change:

Qualification of the LM3401MM* family of products (8L - VSSOP) in both Amkor Philippines (AP1) and ASE Shanghai (ASEH) for Assembly and test. Material comparison as follows:

	Carsem	AP1	ASESH
Mold Compound	8096692	**101325958**	**EN2000515**
Mount Compound	8096585	**101374994**	**EY1000063**
Bond Wire	1.0 Mil Dia., Au	**1.0mil Diameter, Au**	**1.0mil Diameter, Au**
Leadframe (Finish, Base)	Matte Sn, Cu	**Matte Sn, Cu**	**NiPdAu, Cu**

Due to higher demand than forecast at the time of offload, we have exhausted all supply from the prior assembly site (Carsem) and must now ship material from the newly qualified assembly sites (Amkor, AP1 & ASE, ASESH). **** For any desired shipments prior to 90 days from the date of this notification, please notify your TI PCN contact immediately of your approval for this PCN. ****

Reason for Change:

The LM3401MM* family of products is no longer being assembled and tested out of the original Assy/Test site (Carsem).

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Sample Product Shipping Label (not actual product label)

Assembly Site

Carsem (CRS)	Assembly Site Origin (22L)	ASO: CRS
Amkor/Philippines (AP1)	Assembly Site Origin (22L)	ASO: AKR
ASE/Shanghai (ASESH)	Assembly Site Origin (22L)	ASO: ASH

Topside Device marking:
Assembly site code for CRS = W
Assembly site code for AKR = 4
Assembly site code for ASH = A

Product Affected:

LM3401MM/NOPB	LM3401MM/S7002589	LM3401MMX/NOPB	LM3401MMX/S7002590

Reference Qualification Data: Approved 7/01/2013

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qualification Device: LM3401MMX/NOPB(MSL 1-260c)

Package Construction Details

Assembly Site:	AP1	Mold Compound:	101325958
# Pins-Designator, Family:	8-DGK, VSSOP	Mount Compound:	101374994
Leadframe (Finish, Base):	Matte Sn, Cu	Bond Wire:	1.0 Mil Dia., Au

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size / Fail		
		Lot 1	Lot 2	Lot 3
**High Temp Operating Life	125C (500, 1000 Hrs)	77/0	--	--
**High Temp. Storage Bake	170C (420 Hrs)	77/0	--	--
**Biased HAST	130C/85%RH (96 Hrs)	77/0	77/0	77/0
**Autoclave 121C	121C, 2 ATM (96 Hrs)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0
Destructive Physical Analysis	Post Temp Cycle (500cyc)	pass	pass	pass

Notes: **Tests received preconditioning sequence: MSL1-260C

Reference Qualification Data: Approved 4/08/2010

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qualification Device: THS4304DGK (MSL 1-260c)

Package Construction Details

Assembly Site:	ASESH	Mold Compound:	EN2000515
# Pins-Designator, Family:	8-DGK, VSSOP	Mount Compound:	EY1000063
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	1.0 Mil Dia., Au

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size / Fail		
		Lot 1	Lot 2	Lot 3
**High Temp Operating Life	155C (240 Hrs)	77/0	77/0	77/0
**High Temp. Storage Bake	170C (420 Hrs)	77/0	77/0	77/0
**Biased HAST	130C/85%RH (96 Hrs)	77/0	77/0	77/0
**Autoclave 121C	121C, 2 ATM (96 Hrs)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	82/0	82/0	82/0
Destructive Physical Analysis	Post Temp Cycle (500cyc)	pass	pass	pass

Notes: **Tests received preconditioning sequence: MSL1-260C

Reference Qualification Data: Approved 4/08/2010			
This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.			
Qualification Device: TLV2545IDGK (MSL 1-260c)			
Package Construction Details			
Assembly Site:	ASESH	Mold Compound:	EN2000515
# Pins-Designator, Family:	8-DGK, VSSOP	Mount Compound:	EY1000063
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	1.0 Mil Dia., Au

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size / Fail		
		Lot 1	Lot 2	Lot 3
**High Temp Operating Life	155C (240 Hrs)	77/0	77/0	77/0
**High Temp. Storage Bake	150C (420 Hrs)	77/0	77/0	77/0
**Biased HAST	130C/85%RH (96 Hrs)	77/0	77/0	77/0
**Autoclave 121C	121C, 2 ATM (96 Hrs)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0
Destructive Physical Analysis	Post Temp Cycle (500cyc)	pass	pass	pass

Notes: **Tests received preconditioning sequence: MSL1-260C

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com